2013 Program

Jan. 28 (Mon)

15:00~16:30 **Technical Tour**

AIST Research Center for Ubiquitous MEMS and Micro Eng. (UMEMSME, Tsukuba)

Jan. 29 (Tue)

***with simultaneous interpretation （日英同時通訳付き）**

Part 1. Project Report

9:00～9:20 **Review**

Prof. Masayoshi Esashi (Core researcher, Tohoku Univ.)

9:20～9:30 **Introduction of AIST Activities on MEMS Commercialization**

Dr. Ryutaro Maeda (Co-Core researcher, AIST)

9:30～10:00 **Massive Parallel Direct Write EB Lithography**

Mr. Hiroshi Miyaguchi (Tohoku Univ.)

10:00~10:30 **Initial Stage Prototyping for Hetero Integration**

Prof. Shuji Tanaka (Tohoku Univ.)

10:30~11:00 **Hands-on Access for Fabrication Facility**

Prof. Kentaro Totsu (Tohoku Univ.)

11:00~11:30 **Production Stage Prototyping for Hetero Integration**

Dr. Takeshi Kobayashi (AIST)

11:30~12:00 **High Efficiency Production of Integrated MEMS**

Dr. Hideki Takagi (AIST)

12:00～13:30 **Lunch and Poster Session**

Part 2. Micro-nano Hetero System Integration Technologies

13:30~14:00 **Microsensors and Integrated Systems**

Prof. Shanhong Xia (Inst. of Electronics Chinese Academy of Sci., China)

14:00～14:30 **SiGe integrated MEMS: test and reliability aspects**

Prof. Ingrid De Wolf (IMEC, Belgium)

14:30～15:00 **3D-Integration for Smart Systems**

Prof. Thomas Gessner (Fraunhofer ENAS, Germany)

15:00～15:15 **Break**

15:15～15:45 **The Quartz to MEMS Oscillator Transition:**
A Technology Revolution Happening Now
Dr. Aaron Partridge (SiTime, USA)

15:45～16:15 **Integrated microsystems for biomedical applications**
Prof. Dim-Lee Kwong (IME, Singapore)

16:15～16:45 **MEMS AlN ultrasonic transducers for low-power gesture interfaces in smartphones**
Prof. Bernhard Boser (U.C.Berkeley, USA)

17:00～18:00 **Panel discussion "Theme: Hetero integration"**
Moderator: Ms. Miwako Waga (Susano Berkeley, Japan)

18:15～20:00 **Exchange Meeting**